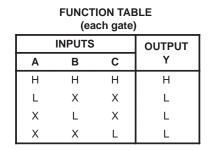
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 Package Options Include Plastic Small-Outline (D) and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

#### description

These devices contain three independent 3-input AND gates. They perform the Boolean function  $Y = A \bullet B \bullet C$  or  $Y = \overline{\overline{A} + \overline{B} + \overline{C}}$  in positive logic.

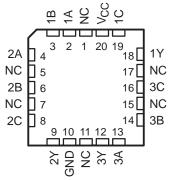
The SN54HC11 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74HC11 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.



SN74HC11 ... D OR N PACKAGE (TOP VIEW) 1A [ 14 VCC 1B 🛛 13 1C 2 2A 🛛 3 12 1Y 2B 🛛 4 🛛 3C 11 2C 🛛 10 3B 5 2Y 🛛 6 9 🛛 3A GND 7 8 3Y

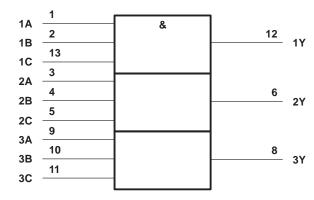
SN54HC11 ... J OR W PACKAGE

SN54HC11 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

## logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, and W packages.

### logic diagram (positive logic)





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### absolute maximum ratings over operating free-air temperature range<sup>†</sup>

Storage temperature range, T <sub>stg</sub>

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

### recommended operating conditions

			S	SN54HC11 S MIN NOM MAX MIN			SN74HC11		
			MIN				NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
	High-level input voltage	$V_{CC} = 2 V$	1.5			1.5			V
VIH		V <sub>CC</sub> = 4.5 V	3.15			3.15			
		$V_{CC} = 6 V$	4.2			4.2			
VIL	Low-level input voltage	V <sub>CC</sub> = 2 V	0		0.5	0		0.5	
		V <sub>CC</sub> = 4.5 V	0		1.35	0		1.35	V
		ACC = 6 A	0		1.8	0		1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
tt		V <sub>CC</sub> = 2 V	0		1000	0		1000	
	Input transition (rise and fall) time	V <sub>CC</sub> = 4.5 V	0		500	0		500	ns
		VCC = 6 V	0		400	0		400	
ТА	Operating free-air temperature		-55		125	-40		85	°C



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PARAMETER	TEST CO		Mar	T <sub>A</sub> = 25°C			SN54HC11		SN74HC11		UNIT
PARAMETER TEST CONDITIONS		Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
		I <sub>OH</sub> = -20 μA	2 V	1.9	1.998		1.9		1.9		
			4.5 V	4.4	4.499		4.4		4.4		
VOH	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		I <sub>OH</sub> = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
	VI = VIH or VIL	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
VOL			6 V		0.001	0.1		0.1		0.1	
		I <sub>OL</sub> = 4 mA	4.5 V 0.17 0.26	0.4		0.33					
		I <sub>OL</sub> = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_{I} = V_{CC} \text{ or } 0,$	I <sub>O</sub> = 0	6 V			2		40		20	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

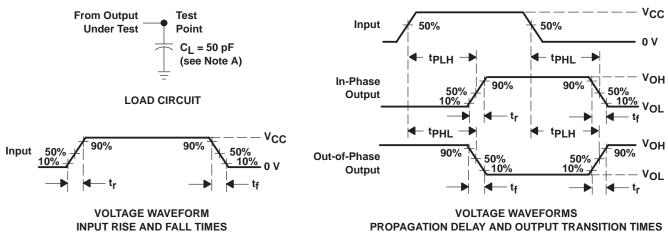
PARAMETER	FROM	TO (OUTPUT)	Vee	T <sub>A</sub> = 25°C			SN54	HC11	SN74HC11		UNIT
FARAWETER	(INPUT)		Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		35	100		150		125	5 ns
<sup>t</sup> pd	A, B, or C	Y	4.5 V		10	20		30		25	
			6 V		8	17		25		21	
			2 V		25	75		110		95	
tt		Y	4.5 V		7	15		22		19	ns
			6 V		5	13		19		16	

# operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate	No load	25	pF



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### PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>r</sub> = 6 ns, t<sub>f</sub> = 6 ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

### Figure 1. Load Circuit and Voltage Waveforms



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